



## Final Product Change Notification

201401019F01

**Issue Date:** 18-Feb-2014  
**Effective Date:** 19-May-2014

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### Change Category

<input checked="" type="checkbox"/> Wafer Fab process	<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Product Marking	<input checked="" type="checkbox"/> Design
<input checked="" type="checkbox"/> Wafer Fab materials	<input type="checkbox"/> Assembly Materials	<input checked="" type="checkbox"/> Electrical spec./Test coverage	<input type="checkbox"/> Mechanical Specification
<input type="checkbox"/> Wafer Fab location	<input type="checkbox"/> Assembly Location	<input type="checkbox"/> Test Location	<input type="checkbox"/> Packing/Shipping/Labeling

Release of 8 inch wafer diameter, change of die pitch size and datasheet for SOT89

### Details of this Change

Release of production using 8 inch wafer diameter and change of die pitch size for PXT2222A and PXT4401 (switching transistors in package SOT89).

Old products: 6 inch wafer diameter and die pitch size of 500µm x 500µm.  
Changed products: 8 inch wafer diameter and die pitch size of 400µm x 400µm.

Production on 8 inch wafer diameter implies the use of the respective 8 inch wafer process technology.

In addition the datasheet for PXT2222A is revised. This change is an editorial one and has no connection to the above mentioned change of wafer diameter and die pitch size. Please refer to the attached Self Qualification Report for details. The revised data sheet will be available for download from our web site ([www.nxp.com](http://www.nxp.com)) soon.

### Why do we Implement this Change

To increase flexibility and volume ramp-up.

### Identification of Affected Products

The products with 8 inch wafer diameter can be identified by date code and different die pitch size.

## Product Availability

### Sample Information

Samples are available upon request  
Latest sample request date for PCN samples is March 19, 2014.

### Production

Planned first shipment 01-May-2014

## Impact

no impact to the product's functionality anticipated.  
No change on external dimensions or mechanical behavior. Electrical and thermal parameters are unchanged (in specification and within the same distribution).

### Data Sheet Revision

A new datasheet will be issued

### Disposition of Old Products

Existing inventory will be shipped until depleted

## Related Notifications

Notification	Issue Date	Effective Date	Title
201110021F0115-	Nov-2011	13-Feb-2012	Release of 8 inch wafer diameter and change of die pitch size for PMBT2222A family

## Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 20-Mar-2014.

## Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please [contact NXP "Global Quality Support Team"](#).

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

**Name** GA Customer Support  
**e-mail address** [DiscrQA.Helpdesk.GA-Products@nxp.com](mailto:DiscrQA.Helpdesk.GA-Products@nxp.com)

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Customer Focus, Passion to Win.

NXP Quality Management Team.

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A global semiconductor company with operations in more than 25 countries, NXP posted unaudited revenue of \$4.36 billion in 2012.

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